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Substitute for form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheats as necessary)	Complete if Known			
	Application Number	Unknown 10/775, 890		
	Filing Date	Even Date Herewith		
	First Named Inventor	Sur, Biswajit		
	Group Art Unit	Unknown		
	Examiner Name	Unknown		
Sheet 1 of 1	Attorney Docket No: 884.319US2			

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